



Material Content Data Sheet



Sales Product Name		TLE9261BQX		Issued		23. January 2018			
MA#		MA001687254							
Package		PG-VQFN-48-31		Weight*		129.39 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.471	1.91	1.91	19101	19101	
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138		
		non noble metal	zinc	7440-66-6	0.072	0.06		554	
		non noble metal	iron	7439-89-6	1.433	1.11		11077	
wire	non noble metal	non noble metal	copper	7440-50-8	58.193	44.97	46.15	449766	461535
		non noble metal	copper	7440-50-8	0.545	0.42	0.42	4214	4214
		encapsulation	organic material	carbon black	1333-86-4	0.188	0.15		1453
	plastics	epoxy resin	-	7.958	6.15		61509		
		inorganic material	silicondioxide	60676-86-0	54.517	42.14	48.44	421358	484320
leadfinish	non noble metal	tin	7440-31-5	2.596	2.01	2.01	20067	20067	
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4744	4744	
glue	plastics	epoxy resin	-	0.179	0.14		1384		
		noble metal	silver	7440-22-4	0.600	0.46	0.60	4635	6019
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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